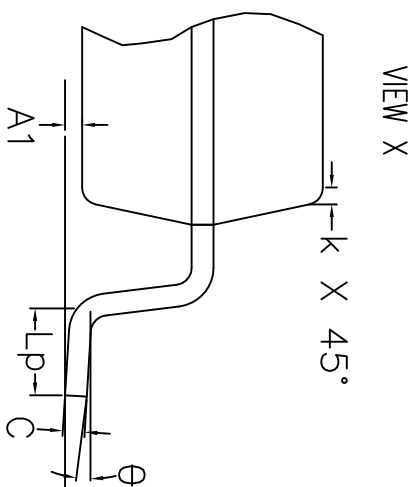
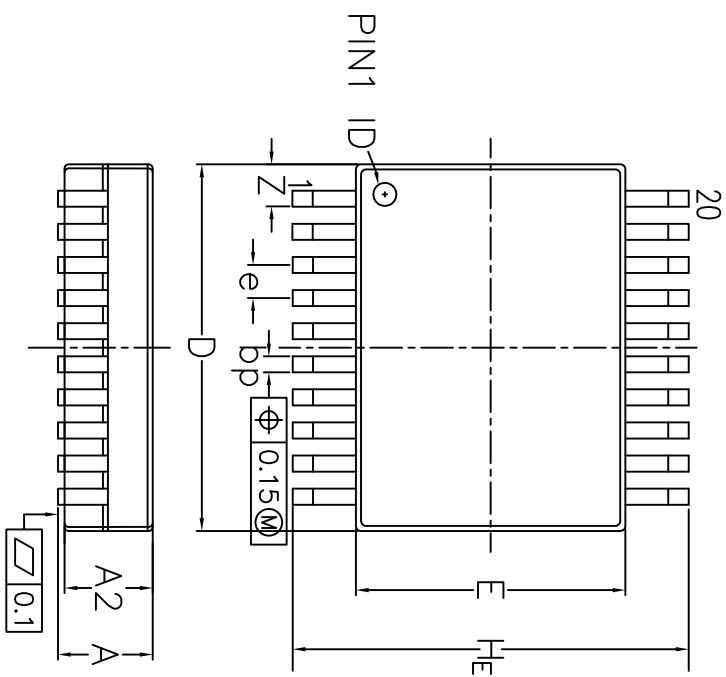


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	2/29/16	J.H



DIMENSIONS OF SUB-GROUP B1	
A max	1.99
bp min	0.25
bp max	0.38
e nom	0.65
He min	7.65
He max	7.90
Lpmin	0.63
Z max	0.74

DIMENSIONS OF SUB-GROUP C1	
A min	1.73
A1 min	0.05
A1 max	0.21
A2 min	1.68
A2 max	1.78
c min	0.09
c max	0.20
D min*	7.07
D max*	7.33
E min*	5.20
E max*	5.38
k min	0.25
θ max	0°
θ max	10°

* WITHOUT MOLD FLASH

- WEIGHT ≤ 0.3 g
- BODY MATERIAL LOW STRESS EPOXY
- LEAD MATERIAL FeNi-ALLOY or Cu-ALLOY
- LEAD FINISH SOLDER PLATING
- LEAD FORM Z-BENDS

TOLERANCES UNLESS SPECIFIED			
DECIMAL	ANGULAR	8024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572	
XXXX±	±	WWW.IDT.COM	
APPROVALS	DATE	TITLE PYG20 PACKAGE OUTLINE	
DRAWN	DATE	SIZE C DRAWING No. PSC-4032-03	
CHECKED		DO NOT SCALE DRAWING	
		SHEET 1 OF 1	